

Schottky Barrier Diode Silicon Epitaxial

CUS10F30

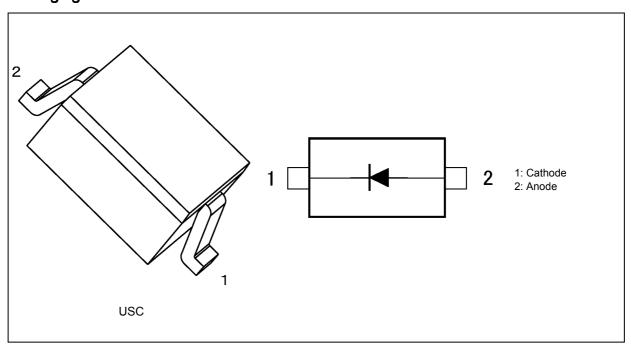
1. Applications

· High-Speed Switching

2. Features

- (1) Low forward voltage: $V_{F(3)} = 0.43 \text{ V (typ.)}$
- (2) General-purpose USC package, equivalent to SOD-323 and SC-76 packages.

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25°C)

Characteristics	Symbol	Note	Rating	Unit
Reverse voltage	V _R	_	30	V
Average rectified current	I _O	(Note 1)	1	Α
Non-repetitive peak forward surge current	I _{FSM}	(Note 2)	5	
Junction temperature	Tj	_	125	°C
Storage temperature	T _{stg}	_	-55 to 125	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on a ceramic circuit board of 25 mm \times 25 mm, Pad dimension of 2 mm \times 2 mm.

Note 2: Measured with a 10 ms pulse.



5. Electrical Characteristics (Unless otherwise specified, T_a = 25°C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _{F(1)}	_	I _F = 10 mA	_	0.22	_	V
	V _{F(2)}		I _F = 100 mA	_	0.28	_	
	V _{F(3)}		I _F = 1 A	_	0.43	0.5	
Reverse current	I _{R(1)}		V _R = 30 V	_	_	50	μΑ
Total capacitance	Ct	_	V _R = 0 V, f = 1 MHz	_	170		pF

6. Marking

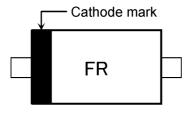


Fig. 6.1 Marking

Marking Code	Part Number		
FR	CUS10F30		

7. Usage Considerations

Schottky barrier diodes (SBDs) have reverse leakage greater than other types of diodes. This makes SBDs
more susceptible to thermal runaway under high-temperature and high-voltage conditions. Thus, both
forward and reverse power losses of SBDs should be considered for thermal and safety design.

8. Land Pattern Dimensions for Reference Only

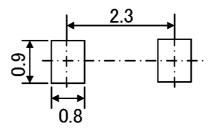


Fig. 8.1 Land Pattern Dimensions for Reference Only (Unit: mm)



9. Characteristics Curves (Note)

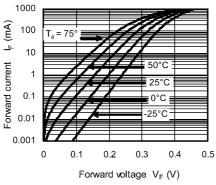


Fig. 9.1 I_F - V_F

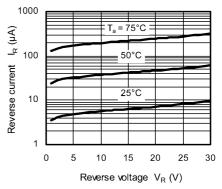


Fig. 9.2 I_R - V_R

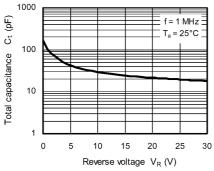


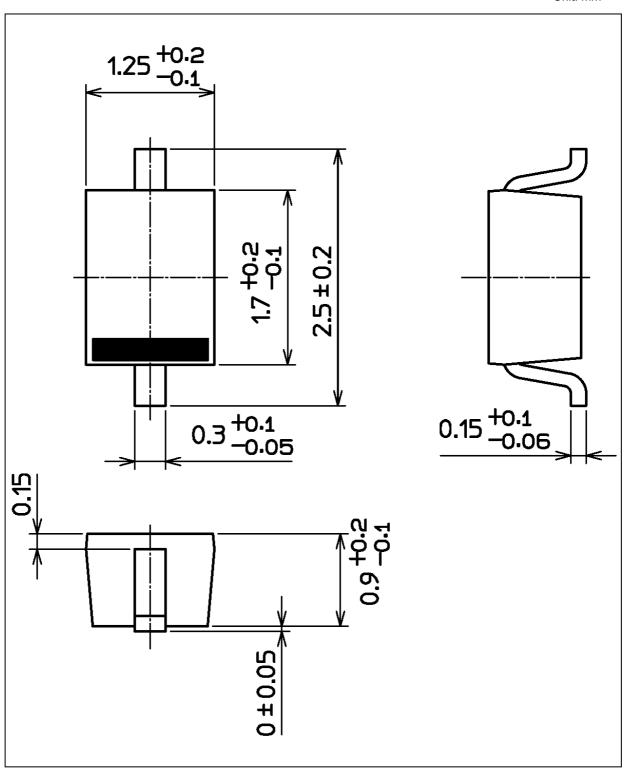
Fig. 9.3 $C_t - V_R$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test.



Package Dimensions

Unit: mm



Weight: 4.5 mg (typ.)

	Package Name(s)	
Nickname: USC		



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